MC14027B

Dual J-K Flip-Flop

The MC14027B dual J–K flip–flop has independent J, K, Clock (C), Set (S) and Reset (R) inputs for each flip–flop. These devices may be used in control, register, or toggle functions.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Logic Edge–Clocked Flip–Flop Design —
  Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive–going edge of the clock pulse
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Pin–for–Pin Replacement for CD4027B

L SUFFIX
CERAMIC
CASE 620
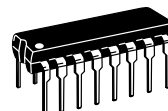
P SUFFIX
PLASTIC
CASE 648
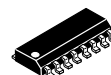
D SUFFIX
SOIC
CASE 751B

ORDERING INFORMATION

MC14XXXBCP	Plastic
MC14XXXBCL	Ceramic
MC14XXXBD	SOIC

$T_A = -55°$ to $125°C$ for all packages.

MAXIMUM RATINGS* (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage	-0.5 to $+18.0$	V
V_{in}, V_{out}	Input or Output Voltage (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I_{in}, I_{out}	Input or Output Current (DC or Transient), per Pin	± 10	mA
P_D	Power Dissipation, per Package†	500	mW
T_{stg}	Storage Temperature	-65 to $+150$	°C
T_L	Lead Temperature (8–Second Soldering)	260	°C

* Maximum Ratings are those values beyond which damage to the device may occur.
†Temperature Derating:
    Plastic "P and D/DW" Packages: -7.0 mW/°C From 65°C To 125°C
    Ceramic "L" Packages: -12 mW/°C From 100°C To 125°C

BLOCK DIAGRAM

V_{DD} = PIN 16
V_{SS} = PIN 8

TRUTH TABLE

Inputs						Outputs*	
C†	J	K	S	R	Q_n‡	Q_{n+1}	$\overline{Q_{n+1}}$
⌐⌐	1	X	0	0	0	1	0
⌐⌐	X	0	0	0	1	1	0
⌐⌐	0	X	0	0	0	0	1
⌐⌐	X	1	0	0	1	0	1
⌐⌐	1	1	0	0	Qo	$\overline{Qo}$	Qo
⌐⌐	X	X	0	0	X	Q_n	$\overline{Q_n}$
X	X	X	1	0	X	1	0
X	X	X	0	1	X	0	1
X	X	X	1	1	X	1	1

No Change

X = Don't Care   ‡ = Present State
† = Level Change   * = Next State

MOTOROLA

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	− 55°C Min	− 55°C Max	25°C Min	25°C Typ #	25°C Max	125°C Min	125°C Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V_{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
$V_{in} = 0$ or V_{DD} "1" Level	V_{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage "0" Level (V_O = 4.5 or 0.5 Vdc) (V_O = 9.0 or 1.0 Vdc) (V_O = 13.5 or 1.5 Vdc)	V_{IL}	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc
		10	—	3.0	—	4.50	3.0	—	3.0	
		15	—	4.0	—	6.75	4.0	—	4.0	
(V_O = 0.5 or 4.5 Vdc) "1" Level (V_O = 1.0 or 9.0 Vdc) (V_O = 1.5 or 13.5 Vdc)	V_{IH}	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
		10	7.0	—	7.0	5.50	—	7.0	—	
		15	11	—	11	8.25	—	11	—	
Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	I_{OH}	5.0	− 3.0	—	− 2.4	− 4.2	—	− 1.7	—	mAdc
		5.0	− 0.64	—	− 0.51	− 0.88	—	− 0.36	—	
		10	− 1.6	—	− 1.3	− 2.25	—	− 0.9	—	
		15	− 4.2	—	− 3.4	− 8.8	—	− 2.4	—	
(V_{OL} = 0.4 Vdc) Sink (V_{OL} = 0.5 Vdc) (V_{OL} = 1.5 Vdc)	I_{OL}	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
		10	1.6	—	1.3	2.25	—	0.9	—	
		15	4.2	—	3.4	8.8	—	2.4	—	
Input Current	I_{in}	15	—	± 0.1	—	±0.00001	± 0.1	—	± 1.0	μAdc
Input Capacitance (V_{in} = 0)	C_{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	I_{DD}	5.0	—	1.0	—	0.002	1.0	—	30	μAdc
		10	—	2.0	—	0.004	2.0	—	60	
		15	—	4.0	—	0.006	4.0	—	120	
Total Supply Current**† (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	I_T	5.0 10 15	I_T = (0.8 μA/kHz) f + I_{DD} I_T = (1.6 μA/kHz) f + I_{DD} I_T = (2.4 μA/kHz) f + I_{DD}							μAdc

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

** The formulas given are for the typical characteristics only at 25°C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L − 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, V = ($V_{DD} − V_{SS}$) in volts, f in kHz is input frequency, and k = 0.002.

PIN ASSIGNMENT

Q_A	1 ●	16	V_{DD}
$\overline{Q}_A$	2	15	Q_B
C_A	3	14	$\overline{Q}_B$
R_A	4	13	C_B
K_A	5	12	R_B
J_A	6	11	K_B
S_A	7	10	J_B
V_{SS}	8	9	S_B

SWITCHING CHARACTERISTICS* (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD}	Min	Typ #	Max	Unit
Output Rise and Fall Time t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 12.5 ns	t_{TLH}, t_{THL}	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Times** 　Clock to Q, Q 　t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 90 ns 　t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 42 ns 　t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 25 ns	t_{PLH}, t_{PHL}	5.0 10 15	— — —	175 75 50	350 150 100	ns
Set to Q, Q 　t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 90 ns 　t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 42 ns 　t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 25 ns		5.0 10 15	— — —	175 75 50	350 150 100	
Reset to Q, Q 　t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 265 ns 　t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 67 ns 　t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 50 ns		5.0 10 15	— — —	350 100 75	450 200 150	
Setup Times	t_{su}	5.0 10 15	140 50 35	70 25 17	— — —	ns
Hold Times	t_h	5.0 10 15	140 50 35	70 25 17	— — —	ns
Clock Pulse Width	t_{WH}, t_{WL}	5.0 10 15	330 110 75	165 55 38	— — —	ns
Clock Pulse Frequency	f_{cl}	5.0 10 15	— — —	3.0 9.0 13	1.5 4.5 6.5	MHz
Clock Pulse Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	— — —	— — —	15 5.0 4.0	μs
Removal Times 　Set	t_{rem}	5 10 15	90 45 35	10 5 3	— — —	ns
Reset		5 10 15	50 25 20	− 30 − 15 − 10	— — —	
Set and Reset Pulse Width	t_{WH}	5.0 10 15	250 100 70	125 50 35	— — —	ns

* The formulas given are for the typical characteristics only at 25°C.
#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
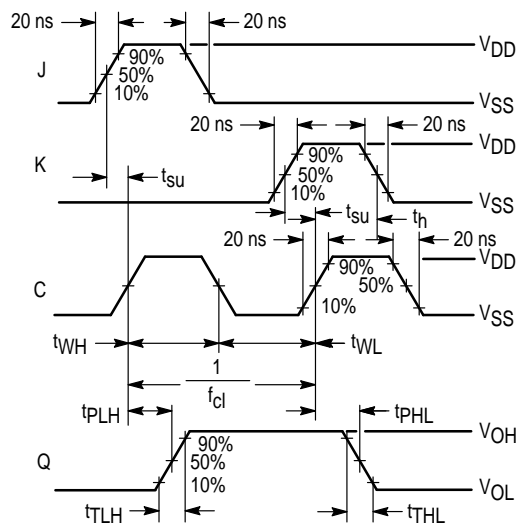
Inputs R and S low.
For the measurement of t_{WH}, I/f_{cl}, and P_D
the Inputs J and K are kept high.

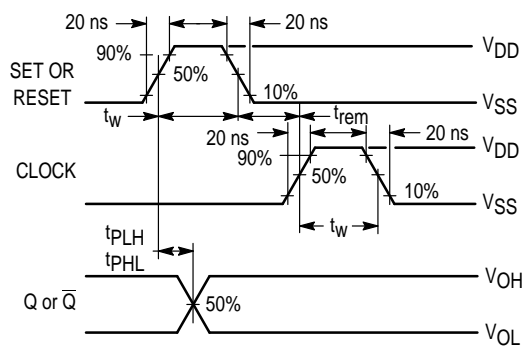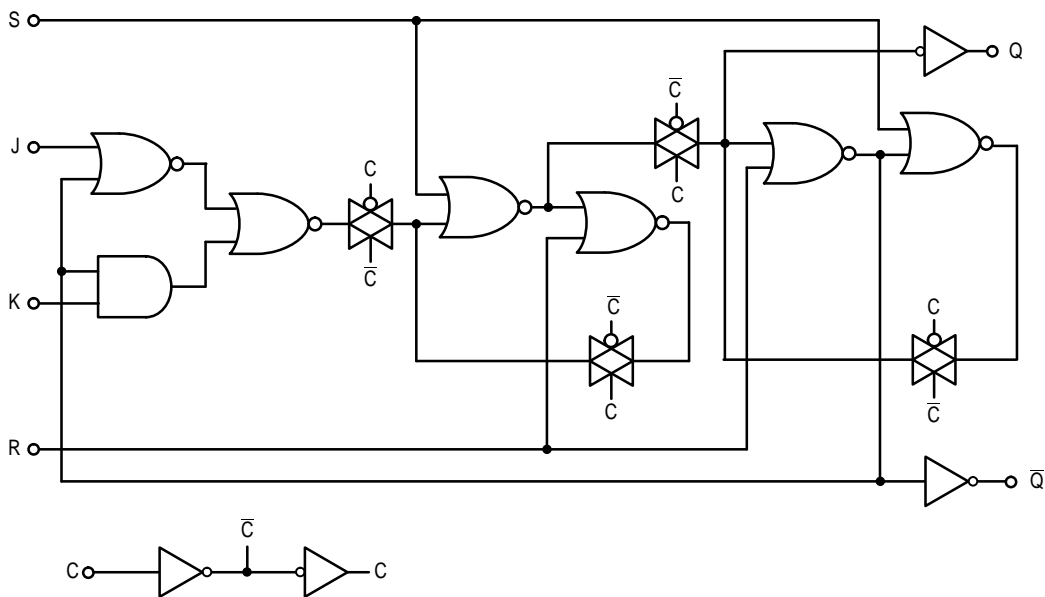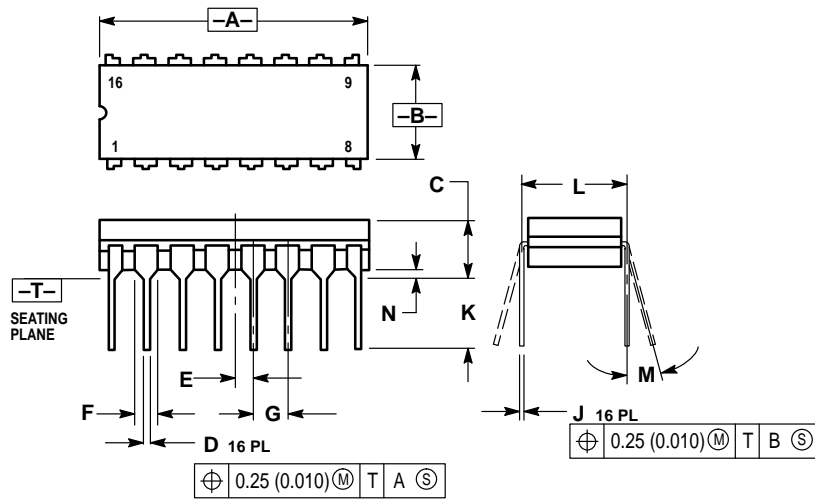**Figure 1. Dynamic Signal Waveforms
(J, K, Clock, and Output)**

**Figure 2. Dynamic Signal Waveforms
(Set, Reset, Clock, and Output)**

LOGIC DIAGRAM
(1/2 of Device Shown)

OUTLINE DIMENSIONS
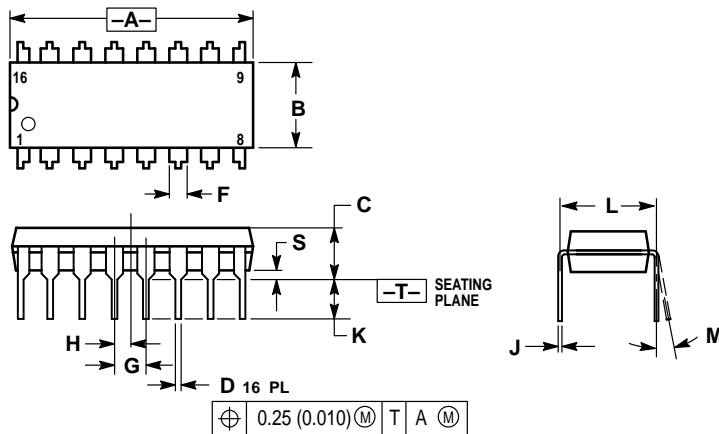
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE V

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	——	0.200	——	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

⊕ 0.25 (0.010) Ⓜ T B Ⓢ

⊕ 0.25 (0.010) Ⓜ T A Ⓢ

P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

⊕ 0.25 (0.010) Ⓜ T A Ⓜ

OUTLINE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J
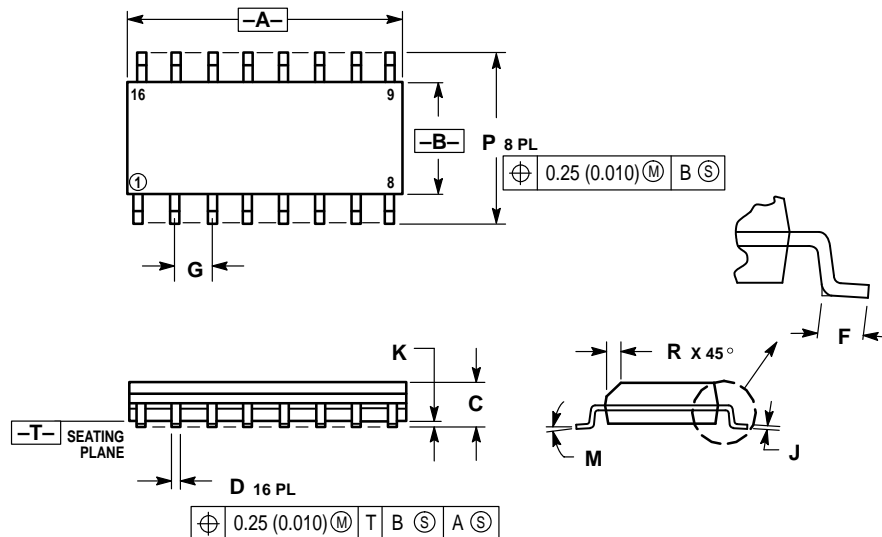
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

MOTOROLA

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